

## **ASMT-CB00**

# InGaN Blue, 0.4 mm Low-Profile Right-Angle Surface-Mount ChipLED

## Overview

The Broadcom<sup>®</sup> ASMT-CB00 blue color chip-type LED is designed with the smallest footprint to achieve high density of components on board. They have the industry standard footprint 1.6 mm x 1.0 mm and a height of only 0.4 mm. This makes them very suitable for cellular phone and mobile equipment backlighting and indication application where space is a constraint. In order to facilitate automated pick-and-place operation, these ChipLEDs are shipped in conductive tape and reel, with 4000 units per reel. These part are compatible with IR soldering.

## **Features**

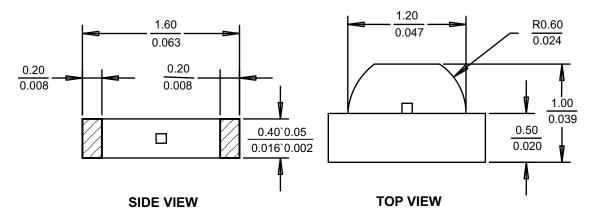
- Small size right-angle mount
- 0603 industry-standard footprint
- 0.4 mm low-profile type
- Operating temperature range of –40°C to +85°C
- Compatible with IR reflow soldering process
- Available in 8 mm tape on 178 mm (7 inch) diameter reels
- Reel sealed in zip-locked moisture barrier bags

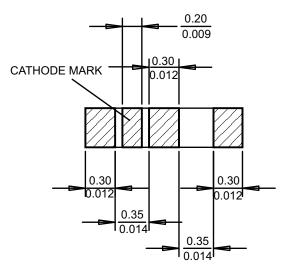
# **Applications**

- LCD Backlighting
- Keypad Side / Backlighting
- Pushbutton backlighting
- Symbol Indicator

**CAUTION!** ASMT-CB00 LEDs are Class 1A ESD sensitive per JESD22-A114C.01. Please observe appropriate precautions during handling and processing. Refer to Application Note AN-1142 for additional details.

# **Package Dimension**





**TERMINAL VIEW** 

## NOTE:

- 1. All dimensions will be in millimeters (inches).
- 2. Tolerance is ±0.1 mm (±0.004 inch) unless otherwise stated.

# **Device Selection Guide**

Package Dimension (mm)	Parts per Reel	Package Description
1.6 (L) x 1.0 (W) x 0.4 (H)	4000	Untinted, Non-diffused

# Absolute Maximum Ratings at $T_A = 25$ °C

Parameter	ASMT-CB00	Unit	
DC Forward Current <sup>a</sup>	10	mA	
Power Dissipation	32	mW	
Reverse Voltage (I <sub>R</sub> = 100 μA)	5	V	
LED Junction Temperature	95	°C	
Operating Temperature Range	-40 to +85	°C	
Storage Temperature Range	-40 to +85	°C	
Soldering Temperature	See reflow soldering profile (Figure 7 and Figure 11)		

a. Derate linearly as shown in Figure 4.

# Electrical Characteristics at T<sub>A</sub> = 25°C

				Thermal Resistance Rθ <sub>J-PIN</sub> (°C/W)
Part Number	Тур.	Max.	Min.	Тур.
ASMT-CB00	2.85	3.15	5	450

a. V<sub>F</sub> tolerance: ±0.1V

# Optical Characteristics at T<sub>A</sub> = 25°C

	_				Viewing Angle 2θ <sub>1/2</sub> <sup>c</sup> (Degrees)
Part Number	Min.	Тур.	Тур.	Тур.	Тур.
ASMT-CB00	7.2	18	469	473	150

a. The luminous intensity  $I_V$  is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the

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b. The dominant wavelength,  $\lambda_d$ , is derived from the CIE Chromaticity Diagram and represents the perceived color of the device.

c.  $\,\theta_{1/2}$  is the off-axis angle where the luminous intensity is ½ the peak intensity.

# Light Intensity (I<sub>V</sub>) Bin Limits<sup>1</sup>

Intensity (mcd)				Intensity (mcd)		
Bin ID	Min.	Max.	Bin ID	Min.	Max.	
Α	0.11	0.18	N	28.50	45.00	
В	0.18	0.29	Р	45.00	71.50	
С	0.29	0.45	Q	71.50	112.50	
D	0.45	0.72	R	112.50	180.00	
Е	0.72	1.10	S	180.00	285.00	
F	1.10	1.80	Т	285.00	450.00	
G	1.80	2.80	U	450.00	715.00	
Н	2.80	4.50	V	715.00	1125.00	
J	4.50	7.20	W	1125.00	1800.00	
K	7.20	11.20	X	1800.00	2850.00	
L	11.20	18.00	Υ	2850.00	4500.00	
M	18.00	28.50				

Tolerance: ±15%

1) Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Broadcom representative for information on current available bins.

# **Color Bin Limits**

# Bin ID Minimum Maximum A 460.0 465.0 B 465.0 470.0 C 470.0 475.0 D 475.0 480.0

Tolerance: ±1 nm

# Forward Voltage (V<sub>F</sub>) Bin Limits

	Forward Voltage (V)		
Bin ID	Minimum	Maximum	
1	2.55	2.75	
2	2.75	2.95	
3	2.95	3.15	

Tolerance: ±0.1V

Figure 1: Relative Intensity vs. Wavelength

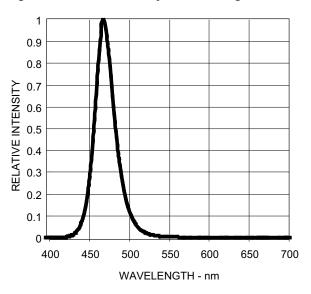


Figure 3: Luminous Intensity vs. Forward Current

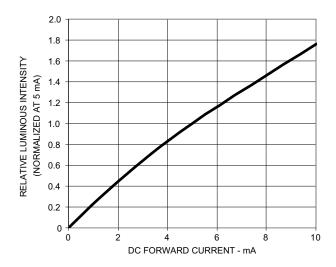


Figure 5: Radiation Pattern

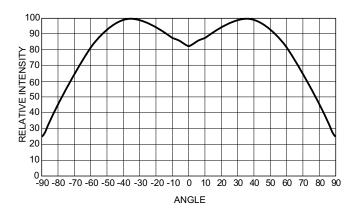


Figure 2: Forward Current vs. Forward Voltage

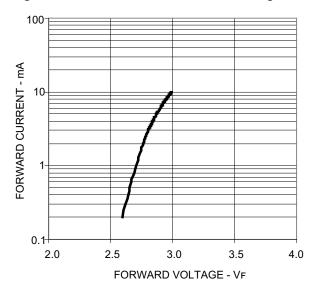


Figure 4: Maximum Forward Current vs. Ambient Temperature

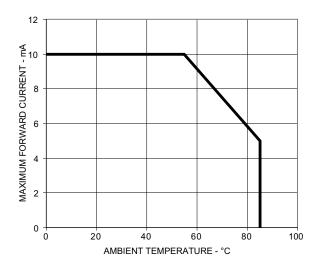
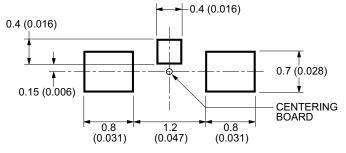


Figure 6: Recommended Soldering Land Pattern



## Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1 mm (±0.004 inch) unless otherwise specified

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Figure 7: Recommended Reflow Soldering Profile

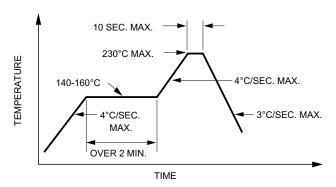


Figure 8: Reeling Orientation

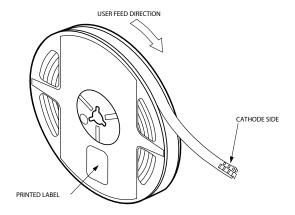
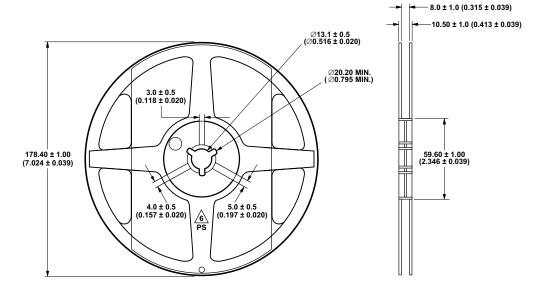


Figure 9: Reel Dimensions

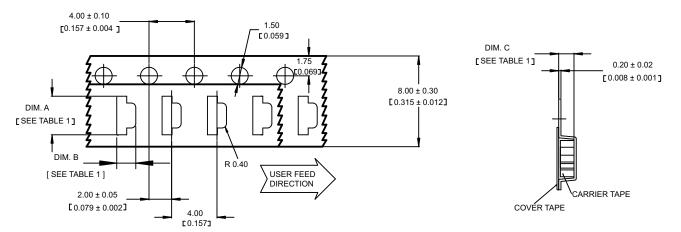


## NOTE:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1 mm (±0.004 inch) unless otherwise specified.

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Figure 10: Tape Dimensions



### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.1$  mm ( $\pm 0.004$  in.) unless otherwise specified.

Table 1

PART NUMBER	DIM. A ±0.10 (0.004)	DIM. B ±0.10 (0.004)	DIM. C ±0.10 (0.004)
ASMT-CB00	1.75 (0.069)	1.10 (0.043)	0.60 (0.024)

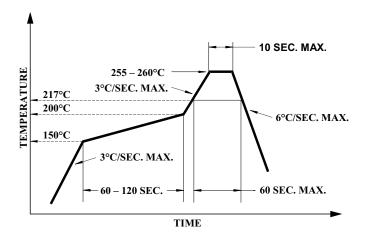
Dimensions in millimeters (inches)

# **Precautionary Notes**

# Soldering

- Do not perform reflow soldering more than twice.
   Observe necessary precautions of handling moisturesensitive device as stated in the following section.
- Do not apply any pressure or force on the LED during reflow and after reflow when the LED is still hot.
- Use reflow soldering to solder the LED. Use hand soldering only for rework if unavoidable, but it must be strictly controlled to following conditions:
  - Soldering iron tip temperature = 310°C max.
  - Soldering duration = 2 seconds max.
  - Number of cycles = 1 only
  - Power of soldering iron = 50W max.
- Do not touch the LED package body with the soldering iron except for the soldering terminals, as it may cause damage to the LED.
- Confirm beforehand whether the functionality and performance of the LED is affected by soldering with hand soldering.

Figure 11: Recommended Pb-free Reflow Soldering Profile



# **Handling Precautions**

This product has a Moisture Sensitive Level 2a rating per JEDEC J-STD-020. Refer to Broadcom Application Note AN5305, *Handling of Moisture Sensitive Surface Mount Devices* for additional details and a review of proper handling procedures.

## ■ Before use:

- An unopened moisture barrier bag (MBB) can be stored at <40°C/90% RH for 12 months. If the actual shelf life has exceeded 12 months and the Humidity Indicator Card (HIC) indicates that baking is not required, then it is safe to reflow the LEDs per the original MSL rating.
- Do not open the MBB prior to assembly (for example, for IQC). If unavoidable, MBB must be properly resealed with fresh desiccant and HIC. The exposed duration must be taken in as floor life.
- Control after opening the MBB:
  - Read the HIC immediately upon opening of MBB.
  - Keep the LEDs at <30°/60%RH at all times, and complete all high temperature-related processes, including soldering, curing or rework within 672 hours.
- Control for unfinished reel:
  - Store unused LEDs in a sealed MBB with desiccant or a desiccator at <5%RH.
- Control of assembled boards:
  - If the PCB soldered with the LEDs is to be subjected to other high-temperature processes, store the PCB in a sealed MBB with desiccant or desiccator at <5% RH to ensure that all LEDs have not exceeded their floor life of 672 hours.
- Baking is required if:
  - The HIC indicator indicates a change in color for 10% and 5%, as stated on the HIC.
  - The LEDs are exposed to conditions of >30°C/60% RH at any time.
  - The LED's floor life exceeded 672 hours.

The recommended baking condition is:  $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 20 hours.

Baking can only be done once.

# **Application Precautions**

- The drive current of the LED must not exceed the maximum allowable limit across temperature as stated in the data sheet. Constant current driving is recommended to ensure consistent performance.
- Circuit design must cater to the whole range of forward voltage (V<sub>F</sub>) of the LEDs to ensure the intended drive current can always be achieved.
- The LED exhibits slightly different characteristics at different drive currents, which may result in a larger variation of performance (meaning: intensity, wavelength, and forward voltage). Set the application current as close as possible to the test current to minimize these variations.
- Driving the LED at low current (< 2 mA) will not cause functional failures to the LED (open/short, for example).
   However, the variation in intensity will be larger than the existing intensity bin ratio.
- If the LED is intended to be used along with LED of other color to achieve color mixing, Broadcom does not guarantee the consistency of the resultant color. Contact Broadcom Sale Representative for such application.
- The LED is not intended for reverse bias. Use other appropriate components for such purposes. When driving the LED in matrix form, ensure that the reverse bias voltage does not exceed the allowable limit of the LED.
- Avoid rapid change in ambient temperature, especially in high-humidity environments, because they cause condensation on the LED.
- If the LED is intended to be used in harsh or outdoor environment, protect the LED against damages caused by rain water, water, dust, oil, corrosive gases, external mechanical stresses, and so on.

## **Eye Safety Precautions**

LEDs may pose optical hazards when in operation. Do not look directly at operating LEDs because it might be harmful to the eyes. For safety reasons, use appropriate shielding or personal protective equipment.

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